

# TIP32

Rev. H Oct.-2018

## / Descriptions

TO-220          PNP          Silicon PNP transistor in a TO-220 Plastic Package.

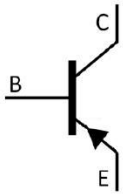
## / Features

TIP31  
Complement to TIP31.

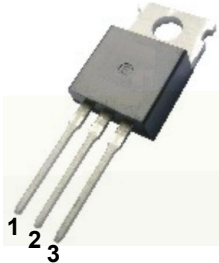
## / Applications

Medium power linear switching applications.

## / Equivalent Circuit



## / Pinning



PIN1 Base          PIN 2 Collector          PIN 3 Emitter

## / $h_{FE}$ Classifications & Marking

See Marking Instructions.

# TIP32

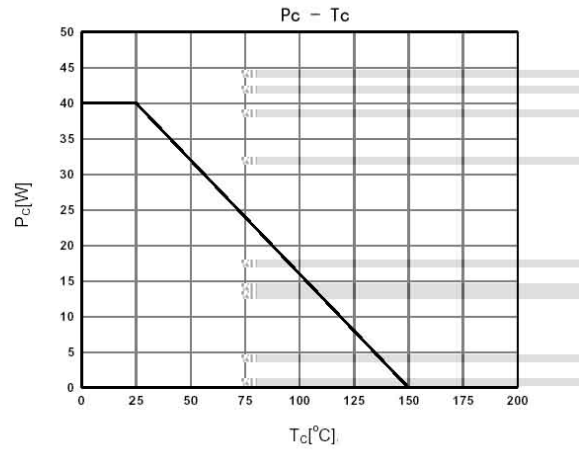
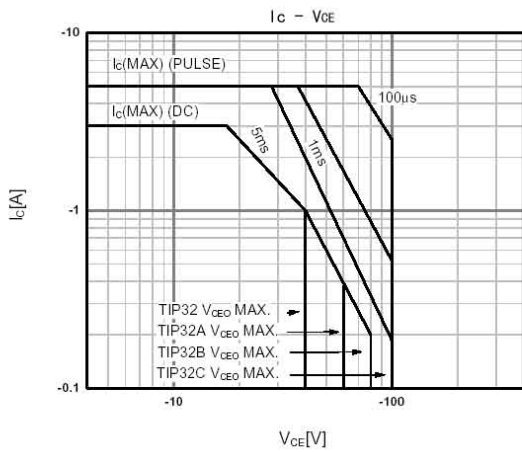
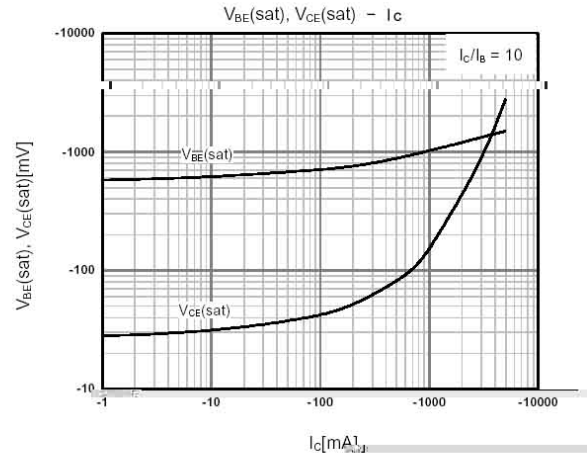
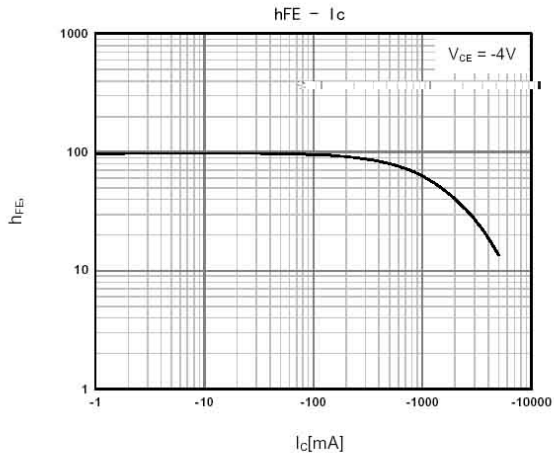
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Parameter	Symbol	Rating				Unit
		TIP32	TIP32A	TIP32B	TIP32C	
Collector to Base Voltage	$V_{CBO}$	-40	-60	-80	-100	V
Collector to Emitter Voltage	$V_{CEO}$	-40	-60	-80	-100	V
Emitter to Base Voltage	$V_{EBO}$	-5.0				V
Collector Current-Continuous	$I_C$	-3.0				A
Peak Collector Current	$I_{CP}$	-5.0				A
Base Current - Continuous	$I_B$	-3.0				A
Collector Power Dissipation	$P_C$	2.0				W
Collector Power Dissipation	$P_C (T_c=25^\circ\text{C})$	40				W
Junction Temperature	$T_j$	150				$^\circ\text{C}$
Storage Temperature Range	$T_{\text{sag}}$	-55~150				$^\circ\text{C}$

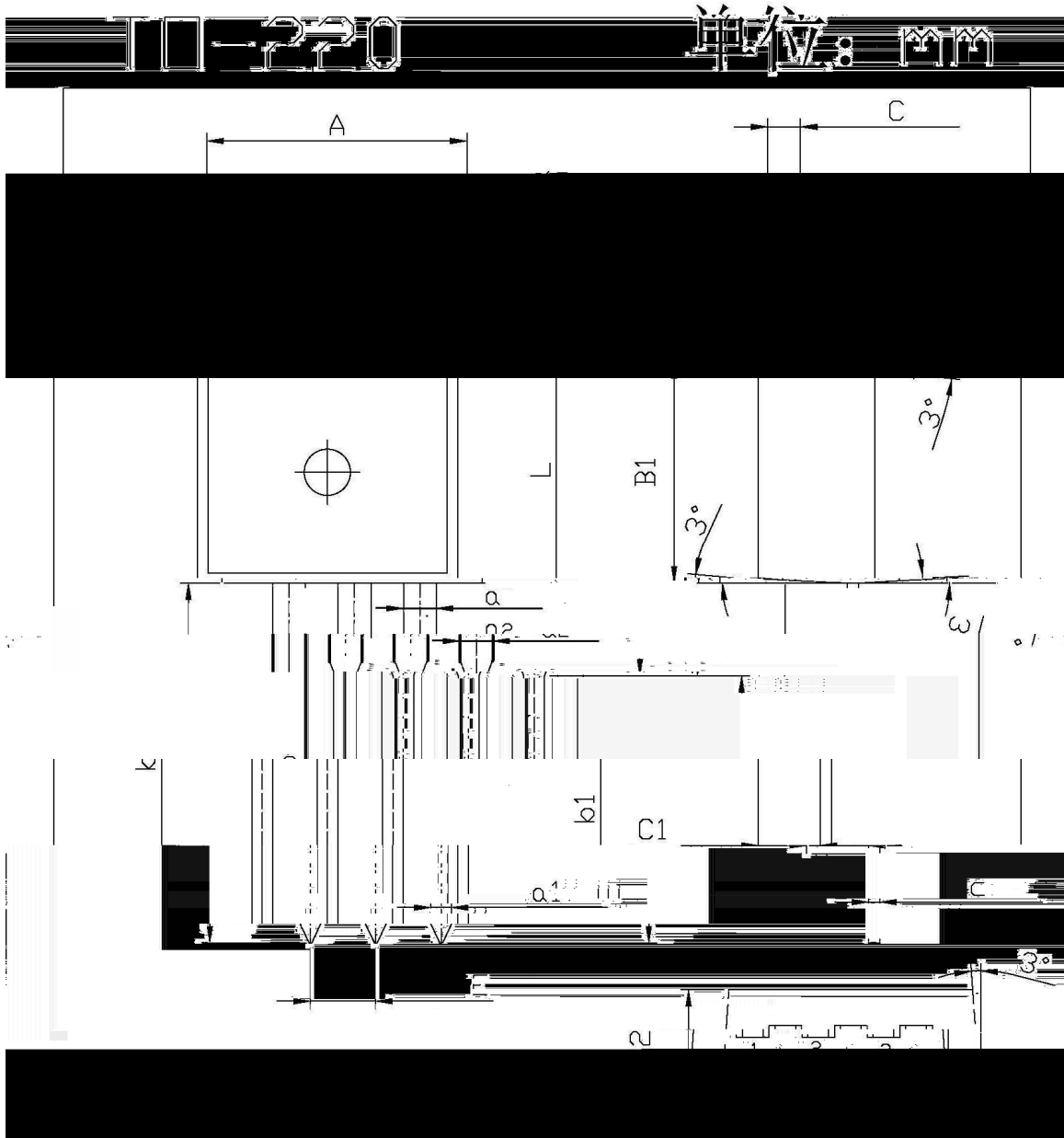
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Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
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/ Electrical Characteristic Curve

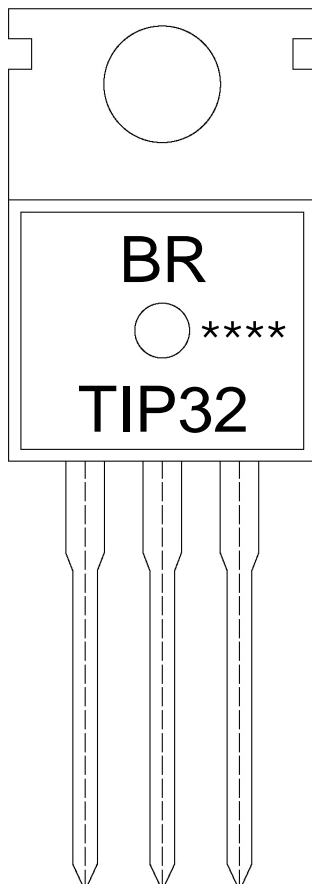


/ Package Dimensions



Symbol	Dimensions in milimeters		Symbol	Dimensions in millimeters	
	Min	Max		Min	Max
A	9.8	10.2	C	1.2	1.4
R	3.56	3.64	B	6.3	6.7
B1	9.0	9.4	L	15.7	
a	1.36	1.42	a1	1.26	1.32
a1	1.65	1.71	a2	1.95	2.01
a2	1.32	1.38	k	0.4	0.6
k	1.32	1.38	b1	0.4	0.6
b1	1.25	1.45			

/ Marking Instructions



BR

TIP32

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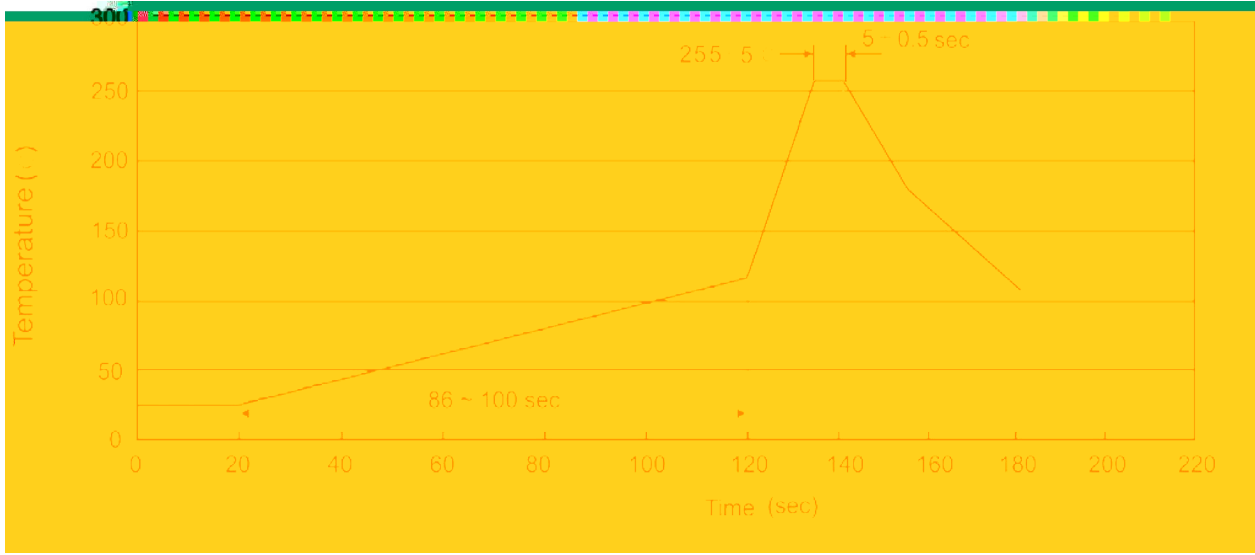
Note:

BR: Company Code

TIP32: Product Type.

\*\*\*\*: Lot No. Code, code change with Lot No.

( ) / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- |   |            |           |   |
|---|------------|-----------|---|
| 1 | 25 150     | 60 90sec; | 1.Preheating:25~150 , Time:60~90sec.    |
| 2 | 255±5      | 5±0.5sec; | 2.Peak Temp.:255±5 , Duration:5±0.5sec. |
| 3 | 2 10 /sec. |           | 3. Cooling Speed: 2~10 /sec.            |

/ Resistance to Soldering Heat Test Conditions

270±5                      10±1 sec.                      Temp.:270±5°C                      Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Bag 只/袋	Bags/Inner Box 袋/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Bag 袋	Inner Box 盒	Outer Box 箱
TO-220/F	200	10	2,000	5	10,000	135×190	237×172×102	560×245×195

/ TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱
TO-220/F	50	20	1,000	5	5,000	532×31.4×5.5	555×164×50	575×290×180

/ Notices